

ABSTRACT

When local heating by use of laser sealing or the like is applied, the bonding strength between glass substrates and a sealing layer is improved to provide an electronic device having increased reliability.

- 5 An electronic device 1 includes a first glass substrate 2, a second glass substrate 3 and a sealing layer 8 to seal an electronic element portion disposed between these glass substrates 2 and 3. The sealing layer 8 is a layer obtained by locally heating a sealing material by an electromagnetic wave, such as laser light or infrared light, to melt-bond the sealing material, the sealing material containing sealing glass, a low-
- 10 expansion filler and an electromagnetic wave absorber. In the first and second glass substrates 1 and 2, each reacted layer 11 is produced to have a maximum depth of at least 30 nm from an interface with the sealing layer.